

AMENDMENTS TO THE CLAIMS

Please amend claims 4, 13, and 24, as set forth in the listing of claims that follows:

1. (Cancelled)

2. (Previously Presented) The component of claim 4, wherein the electrical component is a substrate having an electrical circuit formed on at least one surface of the substrate and at least one semi-conductor chip electrically connected to the electrical circuit.

3. (Cancelled)

4. (Currently Amended) An ~~encapsulated, overmolded and/or underfilled~~ electrical component, comprising:

a circuit board substrate having an electrical circuit;

a semi-conductor chip overlying the substrate and spaced apart therefrom by a distance of about 10 micrometers to about 150 micrometers, thereby creating a space between the circuit board substrate and the semi-conductor chip;

solder interconnections located within the space and connecting the electrical circuit to the semiconductor chip; and

a polymeric overmolding encapsulating the semi-conductor chip on the substrate and filling the space between the semi-conductor chip and the substrate about the solder interconnections, an electrical component encapsulated, overmolded and/or underfilled with said polymeric overmolding being composed of a polymeric composite including a synthetic resin matrix and inorganic filler particles substantially uniformly distributed in the synthetic resin matrix, the inorganic filler particles having a platelet structure defined by opposite substantially flat and substantially parallel faces and being characterized by a dimensions between about 1 and 700 nanometers, the inorganic filler particle content being 20 percent or less by weight based on the weight of the polymeric composite.

5. (Previously Presented) The component of claim 4, wherein the inorganic filler particle content is 15 percent or less by weight based on the weight of the polymeric composite.

6. (Previously Presented) The component of claim 4, wherein the inorganic filler particle is a smectite clay mineral.

7. (Original) The component of claim 6, wherein the smectite clay mineral is montmorillonite.

8. (Previously Presented) The component of claim 4, wherein the synthetic resin matrix is a thermoset resin.

9. (Original) The component of claim 8, wherein the thermoset resin is selected from epoxy, phenolic, polyurethane and polyurea resins.

10. (Previously Presented) The component of claim 4, wherein the synthetic resin matrix is a thermoplastic resin.

11. (Original) The component of claim 10, wherein the thermoplastic resin is selected from polyamides, copolyamides, polycarbonates, polyesters and copolyesters.

12. (Previously Presented) The component of claim 4, wherein the polymeric composite has a CTE from about 5 to 20 ppm/ $^{\circ}$ C.

13. (Currently Amended) An ~~encapsulated, overmolded and/or underfilled~~ electrical component, comprising:

a circuit board substrate having an electrical circuit;

a semi-conductor chip overlying the substrate spaced apart therefrom by a distance of from about 10 micrometers to about 150 micrometers to create a space therebetween;

a plurality of solder interconnections connecting the electrical circuit trace to the semiconductor chip; and

a polymeric overmolding encapsulating the semi-conductor chip on the substrate and filling the space between the semiconductor chip and the substrate, an electrical component ~~encapsulated, overmolded and/or underfilled with~~ said overmolding being formed of a polymeric composite including a thermoplastic resin matrix and an inorganic particulate filler.

14-15. (Cancelled)

16. (Previously Presented) The component of claim 13, wherein the inorganic particulate filler content is 20 percent or less by weight based on the weight of the polymeric composite.

17. (Previously Presented) The component of claim 13, wherein the inorganic particulate filler content is 15 percent or less by weight based on the weight of the polymeric composite.

18. (Previously Presented) The component of claim 13, wherein the inorganic particulate filler is a smectite clay mineral.

19. (Original) The component of claim 18, wherein the smectite clay mineral is montmorillonite.

20. (Previously Presented) The component of claim 13, wherein the thermoplastic resin matrix comprises a resin selected from the group consisting of polyamides, copolyamides, polyesters, copolyesters and polycarbonates.

21. (Original) The component of claim 13, wherein the inorganic particulate filler is glass spheres.

22. (Original) The component of claim 21, wherein the glass spheres have an average diameter of from about 1 micrometer to about 50 micrometers.

23. (Canceled)

24. (Currently Amended) An ~~encapsulated, overmolded and/or underfilled~~ electrical component, comprising:

a substrate having an electrical circuit;

a semi-conductor chip electrically connected to the substrate, the semi-conductor chip being spaced from the substrate by a distance of from about 10 micrometers to about 150 micrometers; and

a polymeric overmolding encasing the component and formed of a polymeric composite, being completely encased within a polymer composite, the semi-conductor chip being completely encased by the substrate and a polymer composite, and/or the said
polymeric overmolding filling said space defined between the semi-conductor chip and
the substrate and overlying a surface of the component opposite the space being filled
with a polymer composite;

wherein the polymer composite includes a synthetic resin matrix and inorganic filler particles substantially uniformly distributed in the synthetic resin matrix, the inorganic filler particles having a platelet structure defined by opposite substantially flat and substantially parallel faces and being characterized by a thickness between about 1
and 20 nanometers and a ratio of a surface area of a face to the thickness of at least 100, the inorganic filler particle content being 20% or less by weight based on the weight of the polymer composite.